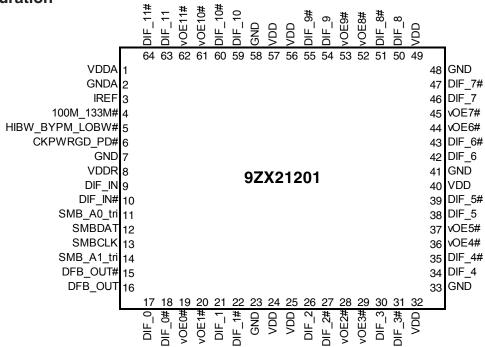
9ZX21201 12-Output Differential Z-buffer for PCIe Gen2/3 and QPI

### **Pin Configuration**



Notes: Pins with ^ prefix have internal ~100K pullup Pins with v prefix have internal ~100K pulldown.

### **Tri-level Input Thresholds**

Level	Voltage
Low	<0.8V
Mid	1.2 <vin<1.8v< td=""></vin<1.8v<>
High	Vin > 2.2V

### Functionality at Power Up (PLL Mode)

100M_133M#	DIF_IN (MHz)	DIF		
1	100.00	DIF_IN		
0	133.33	DIF_IN		

### PLL Operating Mode Readback Table

HiBW_BypM_LoBW#	Byte0, bit 7	Byte 0, bit 6
Low (Low BW)	0	0
Mid (Bypass)	0	1
High (High BW)	1	1

### **PLL Operating Mode**

HiBW_BypM_LoBW#	MODE
Low	PLL Lo BW
Mid	Bypass
High	PLL Hi BW

### NOTE: PLL is OFF in Bypass Mode IDT<sup>®</sup> 12-Output Differential Z-buffer for PCIe Gen2/3 and QPI

### MLF Power Connections

	Pin Number	ſ	
VDD	VDD	GND	Description
1		2	Analog PLL
8		7	Analog Input
24,40,57	25,32,49,56	23,33,41,48, 58	DIF clocks

### 9ZX21201 SMBus Addressing

Pi	n	SMBus Address
SMB_A1_tri	SMB_A0_tri	(Rd/Wrt bit = 0)
0	0	D8
0	М	DA
0	1	DE
М	0	C2
М	М	C4
М	1	C6
1	0	CA
1	М	CC
1	1	CE

### **Pin Description**

PIN #	PIN NAME	TYPE	DESCRIPTION
1	VDDA	PWR	3.3V power for the PLL core.
2	GNDA	PWR	Ground pin for the PLL core.
3	IREF	OUT	This pin establishes the reference for the differential current-mode output pairs. It requires a fixed precision resistor to ground. 475ohm is the standard value for 100ohm differential impedance. Other impedances require
4	100M_133M#	IN	different values. See data sheet. 3.3V Input to select operating frequency See Functionality Table for Definition
5	HIBW_BYPM_LOBW#	IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
6	CKPWRGD_PD#	IN	Notifies device to sample latched inputs and start up on first high assertion, or exit Power Down Mode on subsequent assertions. Low enters Power Down Mode.
7	GND	PWR	Ground pin.
8	VDDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
9	DIF_IN	IN	0.7 V Differential TRUE input
10	DIF_IN#	IN	0.7 V Differential Complementary Input
11	SMB_A0_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SMB_A1 to decode 1 of 9 SMBus Addresses.
12	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
13	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
14	SMB_A1_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SMB_A0 to decode 1 of 9 SMBus Addresses.
15	DFB_OUT#	OUT	Complementary half of differential feedback output, provides feedback signal to the PLL for synchronization with input clock to eliminate phase error.
16	DFB_OUT	OUT	True half of differential feedback output, provides feedback signal to the PLL for synchronization with the input clock to eliminate phase error.
17	DIF_0	OUT	0.7V differential true clock output
18	DIF_0#	OUT	0.7V differential Complementary clock output
19	vOE0#	IN	Active low input for enabling DIF pair 0. 1 =disable outputs, 0 = enable outputs
20	vOE1#	IN	Active low input for enabling DIF pair 1. 1 =disable outputs, 0 = enable outputs
21	DIF_1	OUT	0.7V differential true clock output
22	DIF_1#	OUT	0.7V differential Complementary clock output
23	GND	PWR	Ground pin.
24	VDD	PWR	Power supply, nominal 3.3V
25	VDD	PWR	Power supply, nominal 3.3V
26	DIF_2	OUT	0.7V differential true clock output
27	DIF_2#	OUT	0.7V differential Complementary clock output
28	vOE2#	IN	Active low input for enabling DIF pair 2. 1 =disable outputs, 0 = enable outputs
29	vOE3#	IN	Active low input for enabling DIF pair 3. 1 =disable outputs, 0 = enable outputs
30	DIF_3	OUT	0.7V differential true clock output
31	DIF_3#	OUT	0.7V differential Complementary clock output
32	VDD	PWR	Power supply, nominal 3.3V

## Pin Description (continued)

00	GND	PWR	
33	-		Ground pin.
34	DIF_4		0.7V differential true clock output
35	DIF_4#	OUT	0.7V differential Complementary clock output
36	vOE4#	IN	Active low input for enabling DIF pair 4
			1 =disable outputs, 0 = enable outputs
37	vOE5#	IN	Active low input for enabling DIF pair 5. This pin has an internal pull-down
			1 =disable outputs, 0 = enable outputs
38	DIF_5	OUT	0.7V differential true clock output
39	DIF_5#	OUT	0.7V differential Complementary clock output
40	VDD	PWR	Power supply, nominal 3.3V
41	GND	PWR	Ground pin.
42	DIF_6	OUT	0.7V differential true clock output
43	DIF_6#	OUT	0.7V differential Complementary clock output
44	vOE6#	IN	Active low input for enabling DIF pair 6. This pin has an internal pull-down
44	VUE0#		1 =disable outputs, 0 = enable outputs
45			Active low input for enabling DIF pair 7. This pin has an internal pull-down
45	vOE7#	IN	1 =disable outputs, 0 = enable outputs
46	DIF_7	OUT	0.7V differential true clock output
47	DIF_7#	OUT	0.7V differential Complementary clock output
48	GND	PWR	Ground pin.
49	VDD	PWR	Power supply, nominal 3.3V
50	DIF_8	OUT	0.7V differential true clock output
51	 DIF 8#	OUT	0.7V differential Complementary clock output
	-		Active low input for enabling DIF pair 8. This pin has an internal pull-down
52	vOE8#	IN	1 =disable outputs, 0 = enable outputs
= 0	050"		Active low input for enabling DIF pair 9. This pin has an internal pull-down
53	vOE9#	IN	1 =disable outputs, 0 = enable outputs
54	DIF_9	OUT	0.7V differential true clock output
55	DIF_9#	OUT	0.7V differential Complementary clock output
56	VDD	PWR	Power supply, nominal 3.3V
57	VDD	PWR	Power supply, nominal 3.3V
58	GND	PWR	Ground pin.
59	DIF_10	OUT	0.7V differential true clock output
60	DIF_10#	OUT	0.7V differential Complementary clock output
			Active low input for enabling DIF pair 10. This pin has an internal pull-down
61	vOE10#	IN	1 = disable outputs, 0 = enable outputs
			Active low input for enabling DIF pair 11. This pin has an internal pull-down
62	vOE11#	IN	1 = disable outputs, 0 = enable outputs
63	DIF_11	OUT	0.7V differential true clock output
64	DIF_11#	OUT	0.7V differential Complementary clock output
07		001	

### **Electrical Characteristics - Absolute Maximum Ratings**

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	МАХ	UNITS	NOTES
3.3V Core Supply Voltage	VDD, VDDA	VDD for core logic and PLL			4.6	V	1,2
Input Low Voltage	V <sub>IL</sub>		GND-0.5			V	1
Input High Voltage	V <sub>IH</sub>	Except for SMBus interface			V <sub>DD</sub> +0.5V	V	1
Input High Voltage	VIHSMB	SMBus clock and data pins			5.5V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Operation under these conditions is neither implied nor guaranteed.

### **Electrical Characteristics - Input/Supply/Common Parameters**

 $T_A = T_{COM}$ ; Supply Voltage  $V_{DD}/V_{DDA} = 3.3 V + -5\%$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	T <sub>COM</sub>	Commmercial range	0		70	°C	1
Input High Voltage	V <sub>IH</sub>	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V <sub>DD</sub> + 0.3	v	1
Input Low Voltage	V <sub>IL</sub>	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	V	1
	I <sub>IN</sub>	Single-ended inputs, $V_{IN} = GND$ , $V_{IN} = VDD$	-5		5	uA	1
Input Current	I <sub>INP</sub>	Single-ended inputs $V_{IN} = 0 V$ ; Inputs with internal pull-up resistors $V_{IN} = VDD$ ; Inputs with internal pull-down resistors	-200		200	uA	1
	F <sub>ibyp</sub>	V <sub>DD</sub> = 3.3 V, Bypass mode	33		150	MHz	2
Input Frequency	F <sub>ipll</sub>	$V_{DD} = 3.3 V$ , 100MHz PLL mode	90	100.00	110	MHz	2
	F <sub>ipll</sub>	V <sub>DD</sub> = 3.3 V, 133.33MHz PLL mode	120	133.33	147	MHz	2
Pin Inductance	L <sub>pin</sub>				7	nH	1
	CIN	Logic Inputs, except DIF_IN	1.5		5	pF	1
Capacitance	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	pF	1,4
	COUT	Output pin capacitance			6	pF	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.300	1	ms	1,2
Input SS Modulation Frequency	f <sub>MODIN</sub>	Allowable Frequency (Triangular Modulation)	30		33	kHz	1
OE# Latency	t <sub>LATOE#</sub>	DIF start after OE# assertion DIF stop after OE# deassertion	4	6	12	clocks	1
Tdrive_PD#	t <sub>DRVPD</sub>	DIF output enable after PD# de-assertion		16	300	us	1,3
Tfall	t <sub>F</sub>	Fall time of control inputs			10	ns	1,2
Trise	t <sub>R</sub>	Rise time of control inputs			10	ns	1,2
SMBus Input Low Voltage	VILSMB				0.8	V	1
SMBus Input High Voltage	VIHSMB		2.1		V <sub>DDSMB</sub>	V	1
SMBus Output Low Voltage	VOLSMB	@ I <sub>PULLUP</sub>			0.4	V	1
SMBus Sink Current	I <sub>PULLUP</sub>	@ V <sub>OL</sub>	4			mA	1
Nominal Bus Voltage	V <sub>DDSMB</sub>	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t <sub>RSMB</sub>	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t <sub>FSMB</sub>	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f <sub>MAXSMB</sub>	Maximum SMBus operating frequency			100	kHz	1,5

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Control input must be monotonic from 20% to 80% of input swing.

<sup>3</sup>Time from deassertion until outputs are >200 mV

<sup>4</sup>DIF\_IN input

<sup>5</sup>The differential input clock must be running for the SMBus to be active

IDT® 12-Output Differential Z-buffer for PCIe Gen2/3 and QPI

### **Electrical Characteristics - DIF\_IN Clock Input Parameters**

T<sub>AMB</sub>=T<sub>COM</sub> unless otherwise indicated, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

					0		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Crossover Voltage - DIF_IN	V <sub>CROSS</sub>	Cross Over Voltage	150		900	mV	1
Input Swing - DIF_IN	V <sub>SWING</sub>	Differential value	300			mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I <sub>IN</sub>	$V_{IN} = V_{DD}, V_{IN} = GND$	-5		5	uA	
Input Duty Cycle	d <sub>tin</sub>	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	J <sub>DIFIn</sub>	Differential Measurement	0		125	ps	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Slew rate measured through +/-75mV window centered around differential zero

### **Electrical Characteristics - DIF 0.7V Current Mode Differential Outputs**

 $T_A = T_{COM}$ ; Supply Voltage  $V_{DD}/V_{DDA} = 3.3 V + -5\%$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on	1	2	4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching, Scope averaging on		8	20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope	660	705	850	mV	1
Voltage Low	VLow		-150	1	150		1
Max Voltage	Vmax	Measurement on single ended signal using		725	1150	mV	1
Min Voltage	Vmin	absolute value. (Scope averaging off)	-300	-22		IIIV	1
Vswing	Vswing	Scope averaging off	300	1407		mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	309	550	mV	1, 5
Crossing Voltage (var)	∆-Vcross	Scope averaging off		22	140	mV	1, 6

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production. IREF = VDD/( $3xR_{R}$ ). For  $R_{R}$  = 412 $\Omega$  (1%),  $I_{REF}$  = 2.7mA.  $I_{OH}$  = 6.4 x  $I_{REF}$  and  $V_{OH}$  = 0.7V @  $Z_{O}$ =85 $\Omega$  differential impedance.

<sup>2</sup> Measured from differential waveform

<sup>3</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

<sup>4</sup> Matching applies to rising edge rate of Clock / falling edge rate of Clock#. It is measured in a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope uses for the edge rate calculations.

<sup>5</sup> Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

<sup>6</sup> The total variation of all Vcross measurements in any particular system. Note that this is a subset of V\_cross\_min/max (V\_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V\_cross\_delta to be smaller than V\_cross absolute.

#### **Electrical Characteristics - Current Consumption**

 $T_A = T_{COM}$ ; Supply Voltage  $V_{DD/}V_{DDA} = 3.3 V + -5\%$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Current	IDDVDD	133MHz, $C_L$ = Full load; VDD rail, Zo=85 $\Omega$		260	275	mA	1
Operating Current	I <sub>DDVDDA</sub>	133MHz, $C_L$ = Full load; VDD rail, Zo=85 $\Omega$		13	20	mA	1
Powerdown Current	I <sub>DDVDDPD</sub>	Power Down, VDD rail, Zo=85 $\Omega$		2	6	mA	1
r owerdown Cunent	I <sub>DDVDDAPD</sub>	Power Down, VDD rail, Zo=85 $\Omega$		1.3	2	mA	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

### **Electrical Characteristics - Skew and Differential Jitter Parameters**

 $T_A = T_{COM}$ ; Supply Voltage  $V_{DD}/V_{DDA} = 3.3 V + -5\%$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
CLK_IN, DIF[x:0]	t <sub>SPO_PLL</sub>	Input-to-Output Skew in PLL mode nominal value @ 25°C, 3.3V	-100	29	100	ps	1,2,4,5,8
CLK_IN, DIF[x:0]	t <sub>PD_BYP</sub>	Input-to-Output Skew in Bypass mode nominal value @ 25°C, 3.3V	2.5	3.7	4.5	ns	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DSPO_PLL</sub>	Input-to-Output Skew Varation in PLL mode across voltage and temperature	-50		50	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DSPO_BYP</sub>	Input-to-Output Skew Varation in Bypass mode across voltage and temperature	-250		250	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DTE</sub>	Random Differential Tracking error beween two 9ZX devices in Hi BW Mode		2.9	5	ps (rms)	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DSSTE</sub>	Random Differential Spread Spectrum Tracking error beween two 9ZX devices in Hi BW Mode		14	75	ps	1,2,3,5,8
DIF{x:0]	t <sub>SKEW_ALL</sub>	Output-to-Output Skew across all outputs (Common to Bypass and PLL mode)		32	65	ps	1,2,3,8
PLL Jitter Peaking	j <sub>peak-hibw</sub>	LOBW#_BYPASS_HIBW = 1	0	1.8	2.5	dB	7,8
PLL Jitter Peaking	j <sub>peak-lobw</sub>	LOBW#_BYPASS_HIBW = 0	0	0.7	2	dB	7,8
PLL Bandwidth	pll <sub>HIBW</sub>	LOBW#_BYPASS_HIBW = 1	2	3.1	4	MHz	8,9
PLL Bandwidth	pll <sub>LOBW</sub>	LOBW#_BYPASS_HIBW = 0	0.7	1.1	1.4	MHz	8,9
Duty Cycle	t <sub>DC</sub>	Measured differentially, PLL Mode	45	49.6	55	%	1
Duty Cycle Distortion	t <sub>DCD</sub>	Measured differentially, Bypass Mode @100MHz	-2	-0.2	2	%	1,10
Jitter, Cycle to cycle	time and	PLL mode		15.7	50	ps	1,11
	t <sub>jcyc-cyc</sub>	Additive Jitter in Bypass Mode		0.1	50	ps	1,11

#### Notes for preceding table:

<sup>1</sup> Measured into fixed 2 pF load cap. Input to output skew is measured at the first output edge following the corresponding input.

<sup>2</sup> Measured from differential cross-point to differential cross-point. This parameter can be tuned with external feedback path, if present.

<sup>3</sup> All Bypass Mode Input-to-Output specs refer to the timing between an input edge and the specific output edge created by it.

<sup>4</sup> This parameter is deterministic for a given device

<sup>5</sup> Measured with scope averaging on to find mean value.

<sup>6.</sup>t is the period of the input clock

<sup>7</sup> Measured as maximum pass band gain. At frequencies within the loop BW, highest point of magnification is called PLL jitter peaking.

<sup>8.</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>9</sup> Measured at 3 db down or half power point.

<sup>10</sup> Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

<sup>11</sup> Measured from differential waveform

### **Electrical Characteristics - Phase Jitter Parameters**

 $T_A = T_{COM}$ ; Supply Voltage  $V_{DD/}V_{DDA} = 3.3 V + -5\%$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
	t <sub>jphPCleG1</sub>	PCIe Gen 1		32	86	ps (p-p)	1,2,3
	t <sub>iphPCleG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.8	3	ps (rms)	1,2
	'jphPCleG2	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		1.9	3.1	ps (rms)	1,2
Phase Jitter, PLL Mode	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.45	1	ps (rms)	1,2,4
		QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.20	0.5	ps (rms)	1,5
	t <sub>jphQPI_SMI</sub>	QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.14	0.3	ps (rms)	1,5
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.12	0.2	ps (rms)	1,5
	t <sub>jphPCleG1</sub>	PCIe Gen 1		0.10	10	ps (p-p)	1,2,3
	t <sub>jphPCleG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.13	0.3	ps (rms)	1,2,6
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.10	0.7	ps (rms)	1,2,6
<i>Additive</i> Phase Jitter, Bypass mode	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.10	0.3	ps (rms)	1,2,4,6
Bypadd mode		QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.09	0.3	ps (rms)	1,5,6
	t <sub>jphQPI_SMI</sub>	QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.09	0.1	ps (rms)	1,5,6
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.09	0.1	ps (rms)	1,5,6

<sup>1</sup> Applies to all outputs.

<sup>2</sup> See http://www.pcisig.com for complete specs

<sup>3</sup> Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

<sup>4</sup> Subject to final radification by PCI SIG.

<sup>5</sup> Calculated from Intel-supplied Clock Jitter Tool v 1.6.4

<sup>6</sup> For RMS figures, additive jitter is calculated by solving the following equation: (Additive jitter)<sup>2</sup> = (total jitter)<sup>2</sup> - (input jitter)<sup>2</sup>

### Power Management Table

Inputs		Co	ntrol Bits/P	Outputs		
CKPWRGD•/PD#	DIF_IN/ DIF_IN#	SMBus EN bit	OE# Pin	DIF(11:0)/ DIF(11:0)#	DFB_OUT/ DFB_OUT#	PLL State
0	Х	Х	Х	Hi-Z <sup>1</sup>	Hi-Z <sup>1</sup>	OFF
		0	Х	Hi-Z <sup>1</sup>	Running	ON
1	Running	1	0	Running	Running	ON
		1	1	Hi-Z <sup>1</sup>	Running	ON

### NOTE:

1. Due to external pull down resistors, HI-Z results in Low/Low on the True/Complement outputs

	Ocenter		Measurement Window							
		1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
SSC OFF	Center Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
DIF	100.00	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2,3
DIF	133.33	7.44925		7.49925	7.50000	7.50075		7.55075	ns	1,2,4

### Clock Periods - Differential Outputs with Spread Spectrum Disabled

### Clock Periods - Differential Outputs with Spread Spectrum Enabled

	Ocurtou			Γ	leasurement	Window				
		1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
SSC ON	Center Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
DIF	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2,3
DIF	133.00	7.44930	7.49930	7.51805	7.51880	7.51955	7.53830	7.58830	ns	1,2,4

### Notes:

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK420BQ/CK410B+ accuracy requirements (+/-100ppm). The 9ZX21201 itself does not contribute to ppm error.

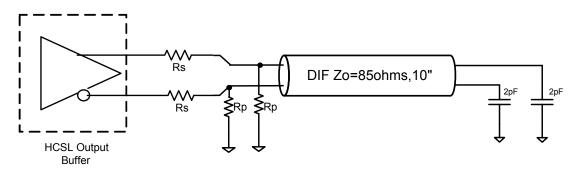
<sup>3</sup> Driven by SRC output of main clock, 100 MHz PLL Mode or Bypass mode

<sup>4</sup> Driven by CPU output of main clock, 133 MHz PLL Mode or Bypass mode

### Differential Output Termination Table

DIF Zo (Ω)	Iref (Ω)	Rs $(\Omega)$	Rp (Ω)
100	475	33	50
85	412	27	42.2 or 43.2

### 9ZX21201 Differential Test Loads



### General SMBus serial interface information for the 9ZX21201

### How to Write:

- Controller (host) sends a start bit.
- Controller (host) sends the write address XX (H)
- IDT clock will *acknowledge*
- Controller (host) sends the beginning byte location = N
- IDT clock will *acknowledge*
- Controller (host) sends the data byte count = X
- IDT clock will *acknowledge*
- Controller (host) starts sending *Byte N through Byte N + X -1*
- IDT clock will *acknowledge* each byte *one at a time*
- Controller (host) sends a Stop bit

Ind	ex Block W	/rit	e Operation			
Cor	ntroller (Host)		IDT (Slave/Receiver)			
Т	starT bit					
Slave	e Address XX <sub>(H)</sub>					
WR	WRite					
			ACK			
Begi	nning Byte = N					
			ACK			
Data	Byte Count = X					
			ACK			
Begir	ining Byte N					
			ACK			
	$\diamond$	te				
	$\diamond$	X Byte	$\diamond$			
	$\diamond$	×	$\diamond$			
			$\diamond$			
Byte	∋ N + X - 1					
			ACK			
Р	stoP bit					

Note: XX<sub>(H)</sub> is defined by SMBus address select pins.

### How to Read:

- Controller (host) will send start bit.
- Controller (host) sends the write address XX (H)
- IDT clock will acknowledge
- Controller (host) sends the begining byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit.
- Controller (host) sends the read addressYY  $_{\rm \scriptscriptstyle (H)}$
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N + X -1
- IDT clock sends Byte 0 through byte X (if X<sub>(H)</sub> was written to byte 8).
- Controller (host) will need to acknowledge each byte
- Controllor (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Ind	lex Block Rea	ad	Operation			
Cor	ntroller (Host)	ID	T (Slave/Receiver)			
Т	starT bit					
Slav	e Address XX <sub>(H)</sub>					
WR	WRite					
			ACK			
Begi	nning Byte = N					
	-		ACK			
RT	Repeat starT					
Slav	e Address YY <sub>(H)</sub>					
RD	ReaD					
			ACK			
		Data Byte Count = X				
	ACK					
			Beginning Byte N			
	ACK					
	^	Byte	 ⊘			
	<u> </u>	XB	○			
	<u> </u>		~			
	~		Byte N + X - 1			
N	Not acknowledge		Byto RTX T			
P	stoP bit					

IDT® 12-Output Differential Z-buffer for PCIe Gen2/3 and QPI

#### Pin # Byte 0 Name **Control Function** 0 Default Type 1 Bit 7 PLL Mode 1 PLL Operating Mode Rd back 1 See PLL Operating Mode Latch 5 R Bit 6 5 PLL Mode 0 PLL Operating Mode Rd back 0 R Readback Table Latch Bit 5 Reserved 0 Bit 4 Reserved 0 Bit 3 **These bits** PLL\_SW\_EN Enable S/W control of PLL BW RW HW Latch S/W Control 0 Bit 2 available in B PLL Mode 1 PLL Operating Mode 1 RW See PLL Operating Mode 1 Bit 1 rev only. PLL Mode 0 PLL Operating Mode 1 RW **Readback Table** 1 100MHz 133MHz Bit 0 4 100M\_133M# Frequency Select Readback R Latch

#### SMBusTable: PLL Mode, and Frequency Select Register

#### SMBusTable: Output Control Register

Byte	1 Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	47/46	DIF_7_En	Output Control - '0' overrides OE# pin	ut Control - '0' overrides OE# pin RW			1
Bit 6	43/42	DIF_6_En	Output Control - '0' overrides OE# pin	RW			1
Bit 5	39/38	DIF_5_En	Output Control - '0' overrides OE# pin	RW			1
Bit 4	35/34	DIF_4_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1
Bit 3	30/31	DIF_3_En	Output Control - '0' overrides OE# pin	RW	LOW/LOW	Enable	1
Bit 2	26/27	DIF_2_En	Output Control - '0' overrides OE# pin	RW	RW RW		1
Bit 1	21/22	21/22 DIF_1_En	Output Control - '0' overrides OE# pin	RW			1
Bit 0	17/18	DIF_0_En	Output Control - '0' overrides OE# pin	RW			1

#### SMBusTable: Output Control Register

Byte	e 2	Pin #	Name	Control Function	Туре	0	1	Default	
Bit 7				Reserved				0	
Bit 6				Reserved				0	
Bit 5				Reserved					
Bit 4				Reserved					
Bit 3	6	4/63	DIF_11_En	Output Control - '0' overrides OE# pin	RW			1	
Bit 2	5	9/60	DIF_10_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1	
Bit 1	5	4/55	DIF_9_En	Output Control - '0' overrides OE# pin	RW	LOW/LOW	Enable	1	
Bit 0	5	0/51	DIF_8_En	Output Control - '0' overrides OE# pin	RW			1	

### SMBusTable: Reserved Register

Byte	3	Pin #	Name	Control Function	Туре	0	1	Default				
Bit 7				Reserved								
Bit 6				Reserved								
Bit 5				Reserved								
Bit 4				Reserved								
Bit 3				Reserved				0				
Bit 2				Reserved				0				
Bit 1				Reserved								
Bit 0				Reserved								

### 9ZX21201 12-Output Differential Z-buffer for PCIe Gen2/3 and QPI

#### SMBusTable: Reserved Register

Byte 4 Pin #		rte 4 Pin # Name		Control Function Ty		0	1	Default
Bit 7		Reserved				0		
Bit 6	Bit 6 Reserved					0		
Bit 5			Reserved				0	
Bit 4			Reserved				0	
Bit 3			Reserved				0	
Bit 2			Reserved				0	
Bit 1			Reserved				0	
Bit 0			Reserved				0	

#### SMBusTable: Vendor & Revision ID Register

Byte 5	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-	RID3		R			Х
Bit 6	-	RID2	REVISION ID	R	A rev = 0000 B rev = 0001		Х
Bit 5	-	RID1		R			Х
Bit 4	-	RID0		R			Х
Bit 3	-	VID3		R			0
Bit 2	-	VID2		R	0001 fo	r IDT/ICS	0
Bit 1	-	VID1	VENDOR ID	R	000110	101/105	0
Bit 0	-	VID0		R	Ī		1

### SMBusTable: DEVICE ID

Byte	6 Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-	D	evice ID 7 (MSB)	R	-		1
Bit 6	-		Device ID 6	R			1
Bit 5	-		Device ID 5	R			0
Bit 4	-		Device ID 4	R	1201 is 201 decimal or C9 hex		0
Bit 3	-		Device ID 3	R			1
Bit 2	-		Device ID 2	R			0
Bit 1	-	Device ID 1		R			0
Bit 0	-		Device ID 0		] [		1

### SMBusTable: Byte Count Register

Byte	Byte 7 Pin # Name		Name	Control Function	Туре	0	1	Default
Bit 7				Reserved				0
Bit 6			Reserved					
Bit 5			Reserved					
Bit 4		-	BC4		RW			0
Bit 3		-	BC3	Writing to this register configures how	RW	Default value	is 8 hex, so 9	1
Bit 2		-	BC2	5 5 5	RW	bytes (0 to 8) w	vill be read back	0
Bit 1		-	BC1	many bytes will be read back.	RW	by de	efault.	0
Bit 0		-	BC0		RW	1		0

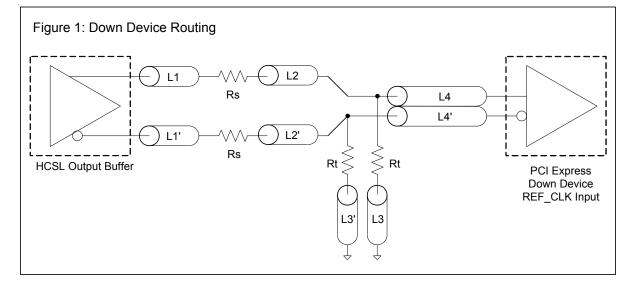
### SMBusTable: Reserved Register

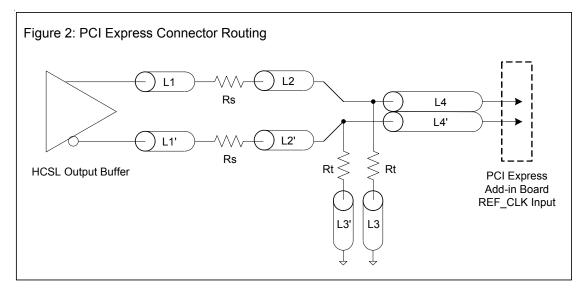
Byte	e 8	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	Bit 7		Reserved				0	
Bit 6			Reserved				0	
Bit 5			Reserved				0	
Bit 4			Reserved				0	
Bit 3			Reserved				0	
Bit 2			Reserved				0	
Bit 1			Reserved				0	
Bit 0			Reserved				0	

DIF Reference Clock							
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure				
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1				
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1				
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1				
Rs	33	ohm	1				
Rt	49.9	ohm	1				

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2





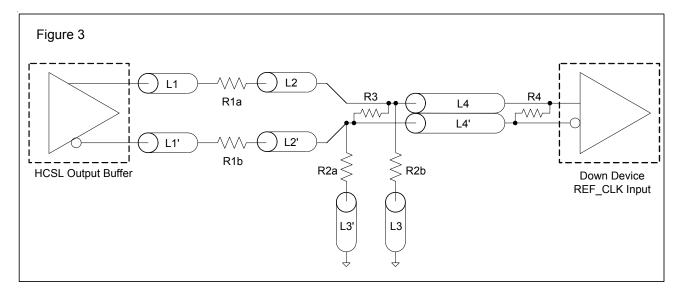
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### 9ZX21201 12-Output Differential Z-buffer for PCIe Gen2/3 and QPI

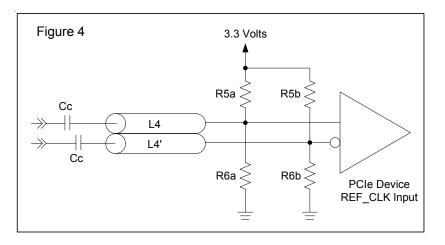
	Alternative Termination for LVDS and other Common Differential Signals (figure 3)								
Vdiff	Vp-р	Vcm	R1	R2	R3	R4	Note		
0.45v	0.22v	1.08	33	150	100	100			
0.58	0.28	0.6	33	78.7	137	100			
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible		
0.60	0.3	1.2	33	174	140	100	Standard LVDS		
P1a = P									

R1a = R1b = R1

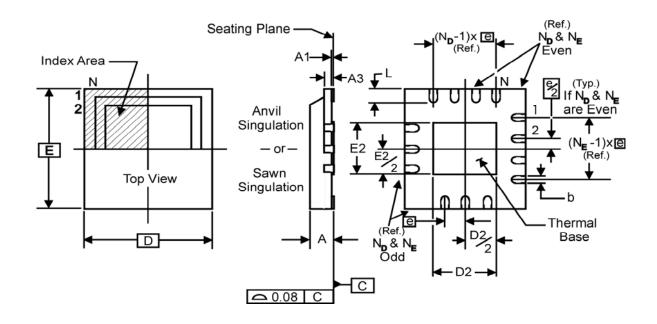
R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)						
Component	Value	Note				
R5a, R5b	8.2K 5%					
R6a, R6b	1K 5%					
Cc	0.1 µF					
Vcm	0.350 volts					



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### THERMALLY ENHANCED, VERY THIN, FINE PITCH QUAD FLAT / NO LEAD PLASTIC PACKAGE

DIMENSIONS

SYMBOL	64L
Ν	64
N <sub>D</sub>	16
N <sub>E</sub>	16

DIMENSIONS (mm)					
SYMBOL	MIN.	MAX.			
А	0.8	1.0			
A1	0	0.05			
A3	0.25 Refe	rence			
b	0.18	0.3			
е	0.50 BA	SIC			
D x E BASIC	9.00 x 9	.00			
D2 MIN. / MAX.	6.00	6.25			
E2 MIN. / MAX.	6.00	6.25			
L MIN. / MAX.	0.30	0.50			

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### **Ordering Information**

Part / Order Number	Shipping Package	Package	Temperature	Difference	
9ZX21201AKLF	Trays	64-pin MLF	0 to +70°C	W/O Byte 0 PLL Control	
9ZX21201AKLFT	Tape and Reel	64-pin MLF	0 to +70°C		
9ZX21201BKLF	Trays	64-pin MLF	0 to +70°C	With Byte 0 PLL Mode	
9ZX21201BKLFT	Tape and Reel	64-pin MLF	0 to +70°C	Control	

"LF" designates PB-free configuration, RoHS compliant.

"A and B" are the device revision designators (will not correlate with the datasheet revision).

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### **Revision History**

Rev.	Issuer	Issue Date	Description	Page #	
A RDW		9/13/2011	1. Updated electrical tables with char data		
	RDW		2. Fixed minor typographical errors	Various	
			3. Moved to final		
B RDW		W 12/8/2011	1. Added B rev functionality description to Features, Benefits		
			2. Updated tDSPO_BYP parameter from +/-350ps to +/-250ps	1,7,11,15	
			3. Updated SMBus Byte 0 with B rev functionality		
			4. Updated ordering information to include B rev		
C RD			1. Updated Power connections table to be consistent with 9ZXL1231.		
	RDW	4/18/20112	2. Updated Rp value for 85 ohm differential Zo from 43.20hms to 42.2 OR	2,9	
			43.2 ohms to be consistent with Intel recommendations.		
D	RDW	5/5/2014	1. Fixed error in feedback path on block diagram		
E	RDW	11/19/2015	1. Updated the DIF_IN Input clock specification to align with the PCIe SIG	6	
			specification.	0	

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(Rev.1.0 Mar 2020)

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